

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	-40°C to +150°C
Contact Force:	58.8mN (6gf) per pin approx.
Actuation Force:	29.6N (3kg)

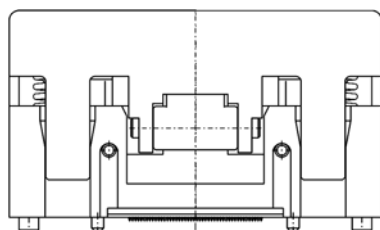
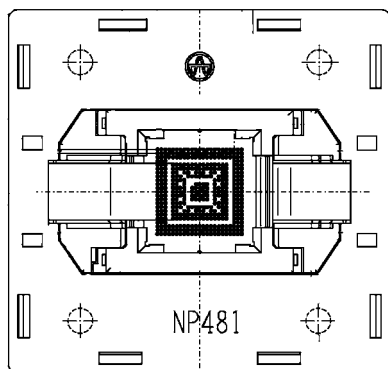
Materials and Finish

Housing:	Polyetherimide (PEI), glass-filled Polyethersulphone (PES), glass-filled
Contacts:	Beryllium Copper (BeCu)
Plating:	Gold over Nickel

Features

- Open top socket for BGA / LGA / CSP packages with 0.4mm pitch.
- 27 x 27 maximum grid size and 12 x 12 maximum body size
- Depopulation versions available
- Compression mount 0.4 to 0.6mm fan-out type

Outline Socket Dimensions



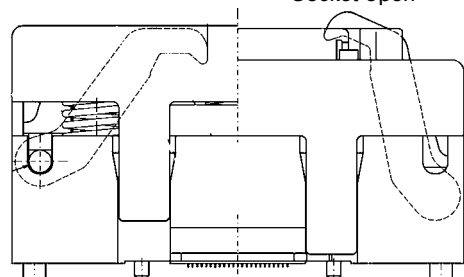
Part Number (Details)

Please Contact Yamaichi

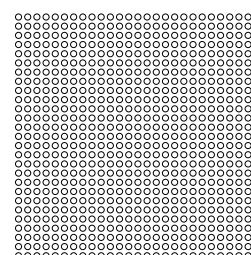


Socket closed

Socket open

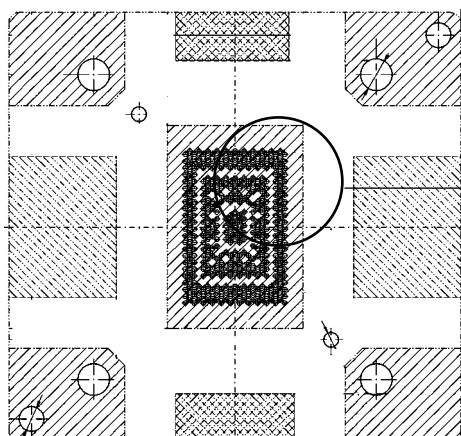


Typical IC Grid Size 27 x 27 (max.)



Typical PCB Layout

Top View from Socket



Detail of Fan-out type

